



BC
#14/E 1/29/02
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Cobbley et al.

Serial No.: 09/639,486

Filed: August 14, 2000

For: METHOD OF ATTACHING SOLDER
BALLS TO BGA PACKAGE UTILIZING A
TOOL TO PICK AND DIP THE SOLDER
BALL IN FLUX

Confirmation No.: 3481

Examiner: Z. Pittman

Group Art Unit: 1725

Attorney Docket No.: 3636.1US
(97-1349.1)

Notice of Allowance Mailed:

August 27, 2002

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

November 19, 2002

Jayna M. Lofgran
Name (Type/Print)

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Box ISSUE FEE
Commissioner for Patents
Washington, D.C. 20231

Sir:

Please amend the above-referenced application as follows:

Match and Return

1

Serial No. 09/639,486

IN THE TITLE:

The title has been amended herein and is shown in clean form below. Pursuant to 37 C.F.R. §§ 1.121 and 1.125 (as amended to date), please enter the title as amended.

E-1

APPARATUS FOR ATTACHING SOLDER BALLS TO BGA PACKAGE
UTILIZING A TOOL TO PICK AND DIP THE SOLDER BALL IN FLUX